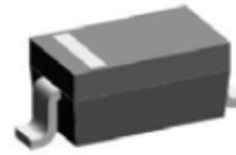


Small Signal Product

200mW, Low VF SMD Schottky Barrier Diode

FEATURES

- Low power loss, high current capability, low V_F
- Surface device type mounting
- Moisture sensitivity level 1
- Matte Tin(Sn) lead finish with Nickel(Ni) underplate
- Pb free version and ROHS compliant
- Green compound (Halogen free) with suffix "G" on packing code and prefix "G" on date code



SOD-323



MECHANICAL DATA

Case : SOD-323 small outline plastic package

Terminals : Matte tin plated, lead free, solderable per MIL-STD-202, method 208 guaranteed

High temperature soldering guaranteed : 260°C/10s

Polarity : Indicated by cathode band

Weight : 0.004grams (approximately)

Marking Code : 5

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNITS
Power dissipation	P_D	200	mW
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	40	V
Mean Forward Current @ 25° C (Lead Temperature)	I_o	30	mA
Non-repetitive peak forward surge current (Note 1)	I_{FSM}	0.2	A
Thermal resistance (Junction to Ambient) (Note 2)	$R_{\theta JA}$	500	°C/W
Junction and storage temperature range	T_J, T_{STG}	-45 to + 125	°C

PARAMETER	SYMBOL	MIN	MAX	UNITS
Forward voltage $I_F=1.0\text{mA}$	V_F	-	0.37	V
Reverse leakage current $V_R=30\text{V}$	I_R	-	0.5	μA
Junction capacitance $V_R=1, f=1.0\text{MHz}$	C_J	2		pF

Notes : 1. Test Condition: 8.3ms single half sine-wave superimposed on rated load (JEDEC method)

Notes : 2. Valid provided that terminals are kept at ambient temperature

Small Signal Product

ORDERING INFORMATION					
PART NO.	PACKING CODE	GREEN COMPOUND CODE	PACKAGE	PACKING	MANUFACTURE CODE
RB751V-40	RR	RRG	SOD-323	3K / 7" Reel	(Note)

Note: Manufacture special control, if empty means no special control requirement.

EXAMPLE					
PREFERRED P/N	PART NO.	PACKING CODE	GREEN COMPOUND CODE	MANUFACTURE CODE	DESCRIPTION
RB751V-40	RB751V-40	RR	G	D0	Green compound

RATINGS AND CHARACTERISTICS CURVES

(TA=25°C unless otherwise noted)

Fig. 1 Typical Forward Characteristics

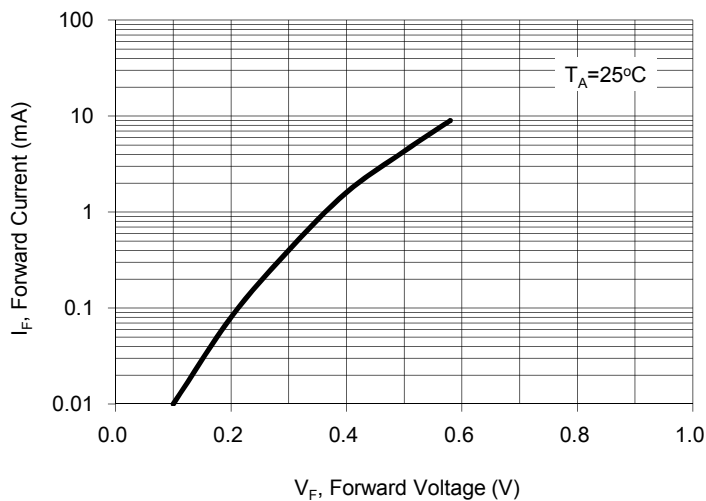


Fig. 2 Forward Current Derating Curve

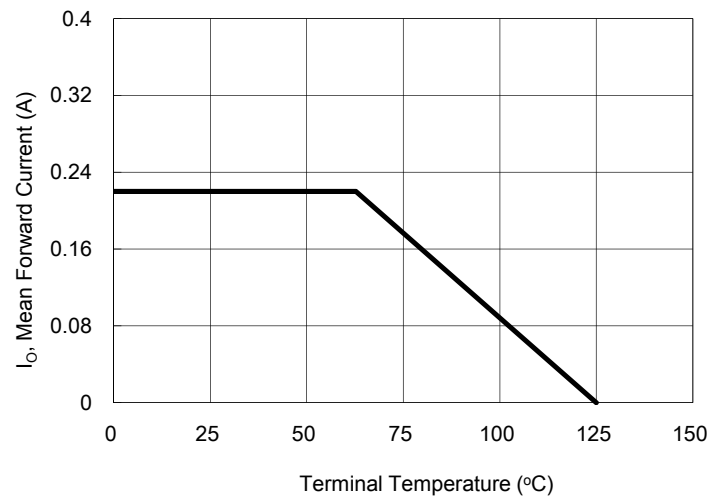


Fig. 3 Admissible Power Dissipation Curve

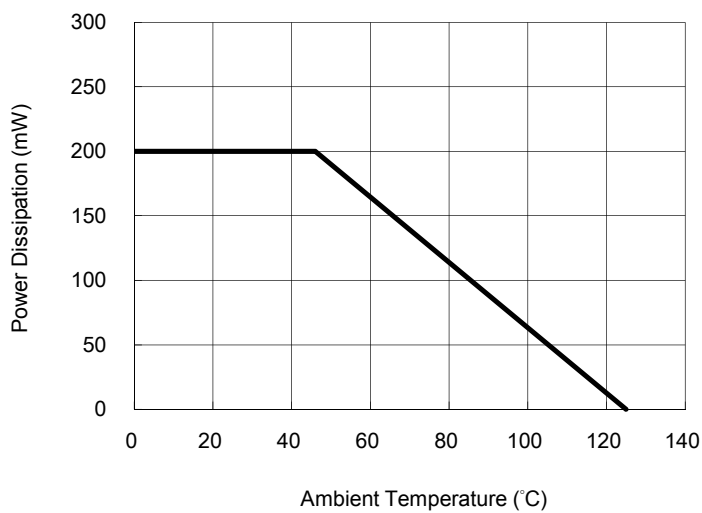
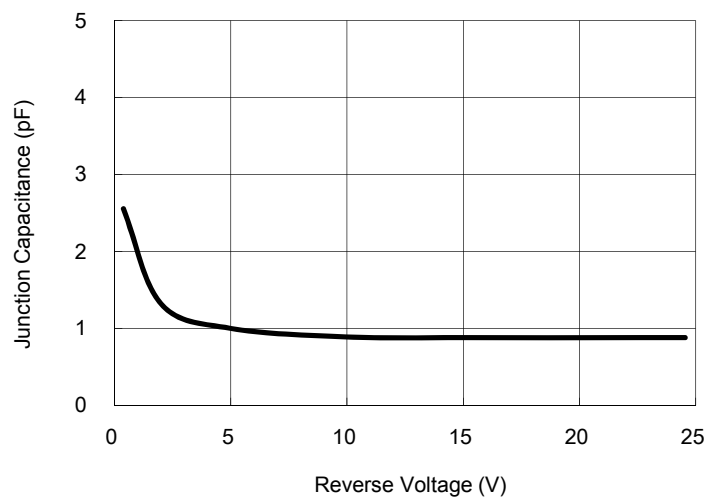
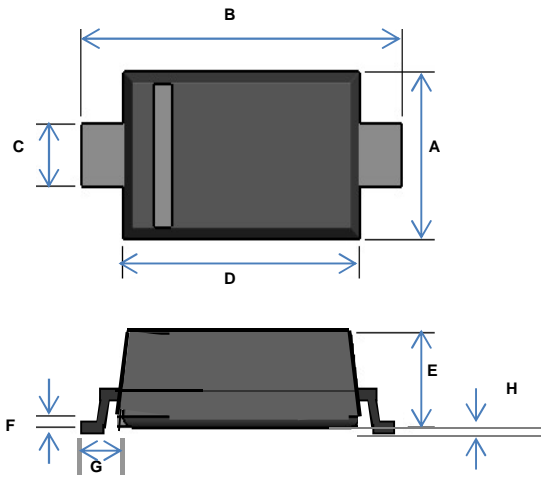


Fig. 4 Typical Junction Capacitance



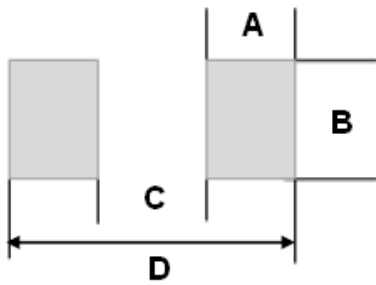
Small Signal Product

DIMENSIONS



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	1.150	1.400	0.045	0.055
B	2.300	2.700	0.091	0.106
C	0.250	0.450	0.010	0.018
D	1.600	1.800	0.063	0.071
E	0.800	1.000	0.031	0.039
F	0.050	0.177	0.002	0.007
G	0.475 REF		0.019 REF	
H	-	0.100	-	0.004

SUGGESTED PAD LAYOUT



DIM.	Unit(mm)	Unit(inch)
	Typ.	Typ.
A	0.63	0.025
B	0.83	0.033
C	1.60	0.063
D	2.86	0.113